

#### N-Channel Enhancement Mode MOSFET

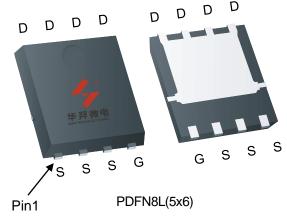
#### **Feature**

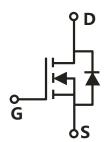
- 40V/143A $R_{DS(ON)} = 2.4 \text{ m}\Omega(typ.) @VGS = 10V$
- 100% Avalanche Tested
- 100% DVDS
- Reliable and Rugged
- Halogen Free and Green Devices Available (RoHS Compliant)

### **Applications**

- Switching application
- Li-battery protection
- DC-DC
- Motor control

## **Pin Description**





Single N-Channel MOSFET

## **Ordering and Marking Information**

Package Code
C2: PDFN8L(5x6)

024N04NS
XYMXXXXX

Date Code
XYMXXXXX

Note: HUAYI halogen free products contain molding compounds and 100% matter tin plate Termi-Nation finish; which are fully compliant with RoHS. HUAYI halogen free products meet or exceed the halogen free require-ments of IPC/JEDEC J-STD-020 for MSL classification at halogen free peak reflow temperature. HUAYI defines "Green" to mean halogen free (RoHS compliant) and halogen free (Br or Cl does not exceed 900ppm by weight in homogeneous material and total of Br and Cl does not exceed 1500ppm by weight).

HUAYI reserves the right to make changes, corrections, enhancements, modifications, and improvements to this pr-oduct and/or to this document at any time without notice.



# **Absolute Maximum Ratings**

Symbol	Parameter	Rating	Unit	
Common Ra	tings (Tc=25°C Unless Otherwise Noted)			
Voss	Drain-Source Voltage		40	V
Vgss	Gate-Source Voltage		±20	V
TJ	Junction Temperature Range		55. 475	°C
Тѕтс	Storage Temperature Range		-55 to 175	°C
ls	Source Current-Continuous(Body Diode) Tc=25°C		143	А
Mounted on	Large Heat Sink		-	•
Ірм	Pulsed Drain Current *	Tc=25°C	428	А
,	Continuous Dunin Comment	Tc=25°C	143	А
lσ	Continuous Drain Current	Tc=100°C	101	А
	M . 5 5	Tc=25°C	106	W
Po	Maximum Power Dissipation Tc=100°C		53	W
R₀uc	Thermal Resistance, Junction-to-Case		1.41	°C/W
R <sub>eJA</sub>	Thermal Resistance, Junction-to-Ambient **		80	°C/W
Eas	Single Pulsed-Avalanche Energy *** L=0.3mH		225	mJ

Note: \*

- \* Repetitive rating; pulse width limited by max.junction temperature.
- \*\* Surface mounted on 1in2 FR-4 board.
- \*\*\* Limited by TJmax , starting TJ=25°C, L = 0.3mH, Rg=  $25\Omega$ , Vgs =10V.

## **Electrical Characteristics**(Tc =25°C Unless Otherwise Noted)

Cumbal	Bananatan	Took Conditions	HYG024N04NS1			11	
Symbol	Parameter	Test Conditions	Min	Тур.	Max	Unit	
Static Cha	Static Characteristics						
BVDSS	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V,I <sub>DS</sub> =250μA	40	-	-	V	
IDSS Drain-to-Source Leakage Current	Drain to Course Leakers Current	V <sub>DS</sub> =40V,V <sub>GS</sub> =0V	-	-	1	μA	
	TJ=125°C	-	-	50	μA		
VGS(th)	Gate Threshold Voltage	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>DS</sub> =250µA	2	3	4	V	
lgss	Gate-Source Leakage Current	Vgs=±20V,Vps=0V	-	-	±100	nA	
RDS(ON)	Drain-Source On-State Resistance	V <sub>GS</sub> =10V,I <sub>DS</sub> =20A	-	2.4	2.9	mΩ	
Diode Cha	racteristics						
VsD	Diode Forward Voltage	Isp=20A,Vgs=0V	-	0.8	1.0	V	
<b>t</b> rr	Reverse Recovery Time	lon-2014 dlon/dt-1001/up	-	23	-	ns	
Qrr	Reverse Recovery Charge	- Isb=20A,dIsb/dt=100A/μs	-	14	-	nC	

# **HYG024N04NS1C2**



# Electrical Characteristics (Cont.) (Tc =25°C Unless Otherwise Noted)

Compleal	Devenuetes	Toot Conditions	HYG024N04NS1			11
Symbol	Parameter	Test Conditions	Min	Тур.	Max	Unit
Dynamic (	Dynamic Characteristics					
Rg	Gate Resistance	V <sub>GS</sub> =0V,V <sub>DS</sub> =0V,F=500KHz	-	2.3	-	Ω
Ciss	Input Capacitance	Vgs=0V,	-	2096	-	
Coss	Output Capacitance	V <sub>DS</sub> =25V,	-	433	-	pF
Crss	Reverse Transfer Capacitance	Frequency=500KHz	-	46	-	
td(ON)	Turn-on Delay Time		-	13	-	
Tr	Turn-on Rise Time	$V_{DD}=20V,R_{G}=3\Omega,$	-	44	-	
td(OFF)	Turn-off Delay Time	los=20A,Vgs=10V	-	25	-	ns
Tf	Turn-off Fall Time		-	8	-	
Gate Charge Characteristics						
Qg	Total Gate Charge(V <sub>GS</sub> =10V)		-	32	-	
Qgs	Gate-Source Charge	V -33V I -30A	-	11	-	nC
Qgd	Gate-Drain Charge	$V_{DS}$ =32V, $I_{DS}$ =20A	-	5.5	-	
V <sub>plateau</sub>	Gate plateau voltage		-	5	-	V

Note: \*Pulse test, pulse width  $\leq 300$ us, duty cycle  $\leq 2\%$ 



### **Typical Operating Characteristics**

**Figure 1: Power Dissipation** 

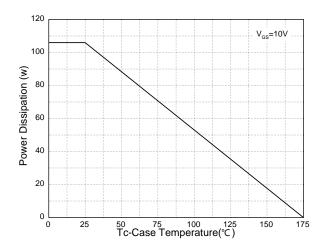
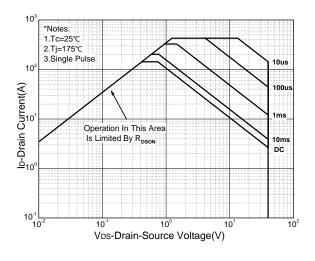
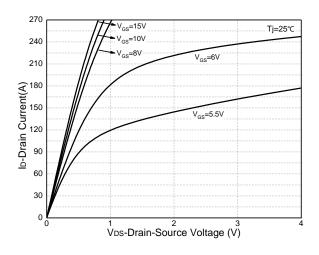


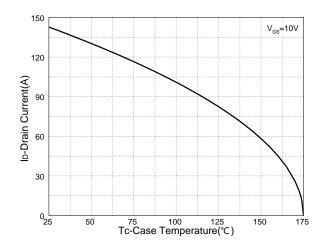
Figure 3: Safe Operation Area



**Figure 5: Output Characteristics** 



**Figure 2: Drain Current** 



**Figure 4: Thermal Transient Impedance** 

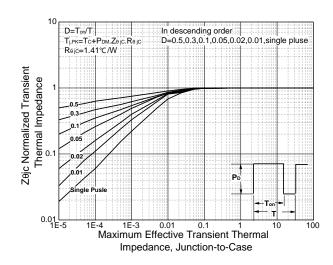
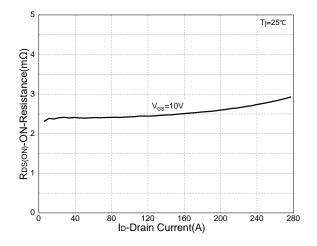


Figure 6: Drain-Source On Resistance





## **Typical Operating Characteristics(Cont.)**

Figure 7: On-Resistance vs. Temperature

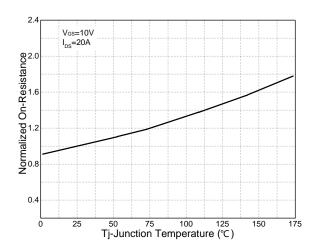


Figure 8: Source-Drain Diode Forward

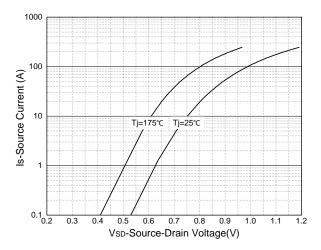
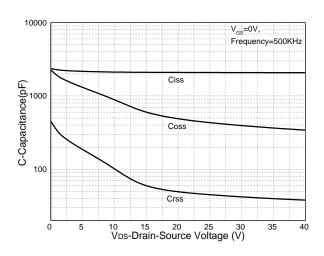
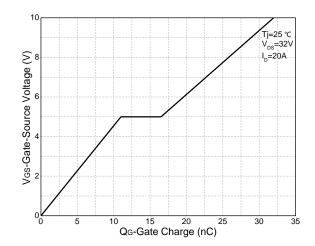


Figure 9: Capacitance Characteristics

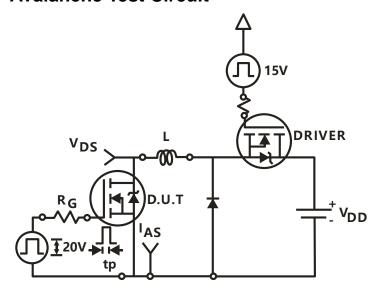


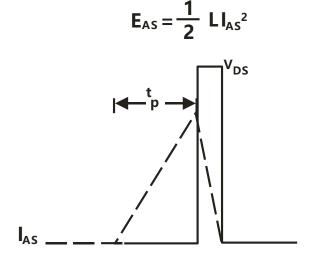
**Figure 10: Gate Charge Characteristics** 



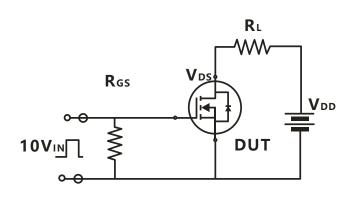


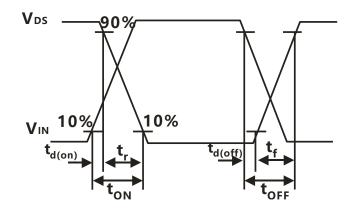
### **Avalanche Test Circuit**



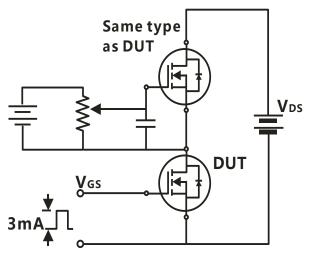


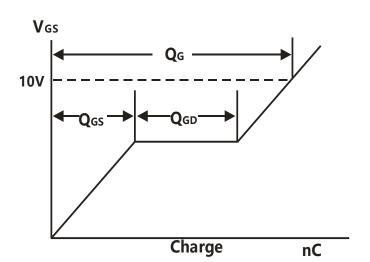
## **Switching Time Test Circuit**





# **Gate Charge Test Circuit**







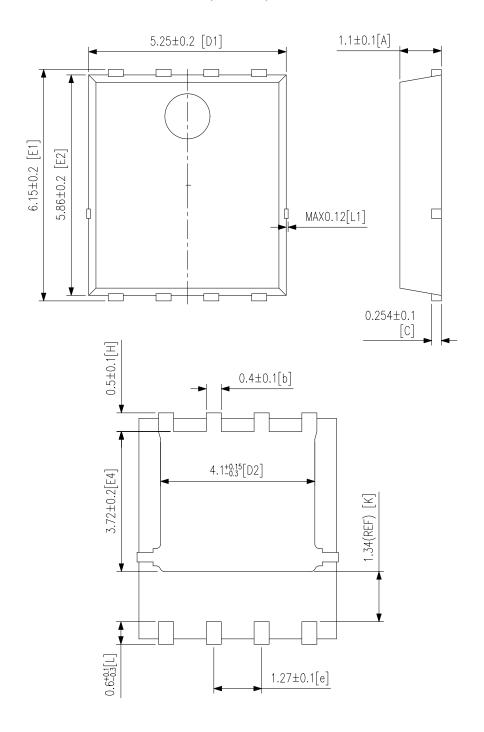
### **Device Per Unit**

Package Type	Unit	Quantity
PDFN8L(5x6)	Reel	5000

## **Package Information**

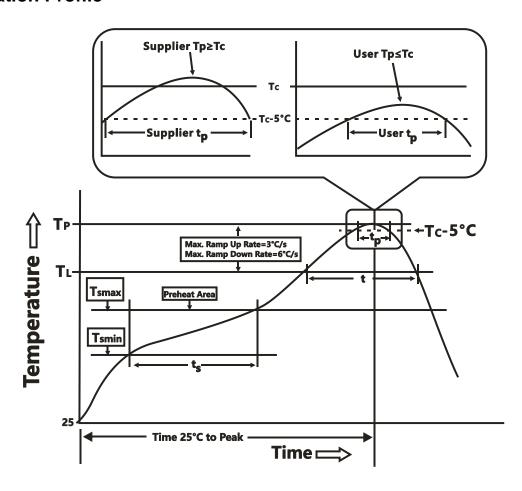
### PDFN8L(5x6)

#### (unit:mm)





#### **Classification Profile**



## **Classification Reflow Profiles**

Profile Feature	Sn-Pb Eutectic Assembly	Pb-Free Assembly	
	Preheat & Soak		
Temperature min (T <sub>smin</sub> )	100 °C	150 °C	
Temperature max (T <sub>smax</sub> )	150 °C	200 °C	
Time (Tsmin to Tsmax) (t <sub>s</sub> )	60-120 seconds	60-120 seconds	
Average ramp-up rate	3 °C/second max.	3°C/second max.	
(T <sub>smax</sub> to T <sub>P</sub> )	5 C/second max.		
Liquidous temperature (T <sub>L</sub> )	183 °C	217 °C	
Time at liquidous (t <sub>L</sub> )	60-150 seconds	60-150 seconds	
Peak package body Temperature	See Classification Temp in table 1	SacClassification Tampin table 2	
(T <sub>p</sub> )*	See Classification Temp in table 1	SeeClassification Tempin table 2	
Time (t <sub>P</sub> )** within 5°C of the specified	20**	30** seconds	
classification temperature (Tc)	20** seconds		
Average ramp-down rate (Tpto Tsmax)	6 °C/second max.	6 °C/second max.	
Time 25°C to peak temperature	6 minutes max.	8 minutes max.	

<sup>\*</sup>Tolerance for peak profile Temperature (Tp) is defined as a supplier minimum and a user maximum.

<sup>\*\*</sup> Tolerance for time at peak profile temperature (t<sub>p</sub>) is defined as a supplier minimum and a user maximum.

### **HYG024N04NS1C2**



Table 1.SnPb Eutectic Process – Classification Temperatures (Tc)

Package Thickness	Volume mm³ <350	Volume mm³ ≥350
<2.5 mm	235 °C	220 °C
≥2.5 mm	220 °C	220 °C

#### Table 2.Pb-free Process – Classification Temperatures (Tc)

Package	Volume mm <sup>3</sup>	Volume mm <sup>3</sup>	Volume mm³
Thickness	<350	350-2000	≥2000
<1.6 mm	260 °C	260 °C	260 °C
1.6 mm – 2.5 mm	260 °C	250 °C	245 °C
≥2.5 mm	250 °C	245 °C	245 °C

### **Reliability Test Program**

Test item	Method	Description
SOLDERABILITY	JESD-22, B102	5 Sec, 245°C
HTRB	JESD-22, A108	168/500 Hrs, Bias @ 150°C
HTGB	JESD-22, A108	168/500 Hrs, V <sub>gs</sub> 100% @ 150°C
PCT	JESD-22, A102	96 Hrs, 100%RH, 2atm, 121°C
тст	JESD-22, A104	250/500 Cycles, -55°C~150°C

#### **Customer Service**

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